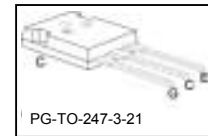
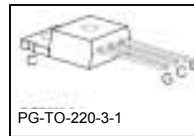
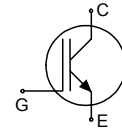


Fast IGBT in NPT-technology

- 75% lower E_{off} compared to previous generation combined with low conduction losses
- Short circuit withstand time – 10 μ s
- Designed for:
 - Motor controls
 - Inverter
- NPT-Technology for 600V applications offers:
 - very tight parameter distribution
 - high ruggedness, temperature stable behaviour
 - parallel switching capability



- Qualified according to JEDEC¹ for target applications
- Pb-free lead plating; RoHS compliant
- Complete product spectrum and PSpice Models : <http://www.infineon.com/igbt/>

Type	V_{CE}	I_C	$V_{CE(sat)}$	T_j	Marking	Package
SGP15N60	600V	15A	2.3V	150°C	G15N60	PG-TO-220-3-1
SGW15N60	600V	15A	2.3V	150°C	G15N60	PG-TO-247-3-21

Maximum Ratings

Parameter	Symbol	Value	Unit
Collector-emitter voltage	V_{CE}	600	V
DC collector current	I_C	31	A
$T_C = 25^\circ\text{C}$		15	
$T_C = 100^\circ\text{C}$			
Pulsed collector current, t_p limited by T_{jmax}	I_{Cpuls}	62	
Turn off safe operating area $V_{CE} \leq 600\text{V}$, $T_j \leq 150^\circ\text{C}$	-	62	
Gate-emitter voltage	V_{GE}	± 20	V
Avalanche energy, single pulse $I_C = 15\text{ A}$, $V_{CC} = 50\text{ V}$, $R_{GE} = 25\ \Omega$, start at $T_j = 25^\circ\text{C}$	E_{AS}	85	mJ
Short circuit withstand time ² $V_{GE} = 15\text{V}$, $V_{CC} \leq 600\text{V}$, $T_j \leq 150^\circ\text{C}$	t_{SC}	10	μ s
Power dissipation $T_C = 25^\circ\text{C}$	P_{tot}	139	W
Operating junction and storage temperature	T_j , T_{stg}	-55...+150	$^\circ\text{C}$
Soldering temperature, wavesoldering, 1.6mm (0.063 in.) from case for 10s	T_s	260	

¹ J-STD-020 and JESD-022

² Allowed number of short circuits: <1000; time between short circuits: >1s.

Thermal Resistance

Parameter	Symbol	Conditions	Max. Value	Unit
Characteristic				
IGBT thermal resistance, junction – case	R_{thJC}		0.9	KW
Thermal resistance, junction – ambient	R_{thJA}	PG-TO-220-3-1 PG-TO-247-3-21	62 40	

Electrical Characteristic, at $T_j = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Conditions	Value			Unit
			min.	Typ.	max.	
Static Characteristic						
Collector-emitter breakdown voltage	$V_{(BR)CES}$	$V_{GE}=0V, I_C=500\mu A$	600	-	-	V
Collector-emitter saturation voltage	$V_{CE(sat)}$	$V_{GE} = 15V, I_C=15A$ $T_j=25^\circ\text{C}$ $T_j=150^\circ\text{C}$	1.7 -	2 2.3	2.4 2.8	
Gate-emitter threshold voltage	$V_{GE(th)}$	$I_C=400\mu A, V_{CE}=V_{GE}$	3	4	5	
Zero gate voltage collector current	I_{CES}	$V_{CE}=600V, V_{GE}=0V$ $T_j=25^\circ\text{C}$ $T_j=150^\circ\text{C}$	- -	- -	40 2000	μA
Gate-emitter leakage current	I_{GES}	$V_{CE}=0V, V_{GE}=20V$	-	-	100	nA
Transconductance	g_{fs}	$V_{CE}=20V, I_C=15A$	3	10.9	-	S
Dynamic Characteristic						
Input capacitance	C_{iss}	$V_{CE}=25V,$ $V_{GE}=0V,$ $f=1\text{MHz}$	-	800	960	pF
Output capacitance	C_{oss}		-	84	101	
Reverse transfer capacitance	C_{riss}		-	52	62	
Gate charge	Q_{Gate}	$V_{CC}=480V, I_C=15A$ $V_{GE}=15V$	-	76	99	nC
Internal emitter inductance measured 5mm (0.197 in.) from case	L_E	PG-TO-220-3-1 PG-TO-247-3-21	- -	7 13	- -	nH
Short circuit collector current ²⁾	$I_{C(SC)}$	$V_{GE}=15V, t_{SC}\leq 10\mu s$ $V_{CC}\leq 600V,$ $T_j\leq 150^\circ\text{C}$	-	150	-	A

²⁾ Allowed number of short circuits: <1000; time between short circuits: >1s.

Switching Characteristic, Inductive Load, at $T_j=25^\circ\text{C}$

Parameter	Symbol	Conditions	Value			Unit
			min.	typ.	max.	
IGBT Characteristic						
Turn-on delay time	$t_{d(\text{on})}$	$T_j=25^\circ\text{C}$, $V_{CC}=400\text{V}$, $I_C=15\text{A}$, $V_{GE}=0/15\text{V}$, $R_G=21\Omega$, $L_{\sigma}^{1)}=180\text{nH}$, $C_{\sigma}^{1)}=250\text{pF}$ Energy losses include "tail" and diode reverse recovery.	-	32	38	ns
Rise time	t_r		-	23	28	
Turn-off delay time	$t_{d(\text{off})}$		-	234	281	
Fall time	t_f		-	46	55	
Turn-on energy	E_{on}		-	0.30	0.36	mJ
Turn-off energy	E_{off}		-	0.27	0.35	
Total switching energy	E_{ts}		-	0.57	0.71	

Switching Characteristic, Inductive Load, at $T_j=150^\circ\text{C}$

Parameter	Symbol	Conditions	Value			Unit
			min.	typ.	max.	
IGBT Characteristic						
Turn-on delay time	$t_{d(\text{on})}$	$T_j=150^\circ\text{C}$ $V_{CC}=400\text{V}$, $I_C=15\text{A}$, $L_{\sigma}^{1)}=180\text{nH}$, $C_{\sigma}^{1)}=250\text{pF}$ $V_{GE}=0/15\text{V}$, $R_G=21\Omega$ Energy losses include "tail" and diode reverse recovery.	-	31	38	ns
Rise time	t_r		-	23	28	
Turn-off delay time	$t_{d(\text{off})}$		-	261	313	
Fall time	t_f		-	54	65	
Turn-on energy	E_{on}		-	0.45	0.54	mJ
Turn-off energy	E_{off}		-	0.41	0.53	
Total switching energy	E_{ts}		-	0.86	1.07	

¹⁾ Leakage inductance L_{σ} and Stray capacity C_{σ} due to dynamic test circuit in Figure E.

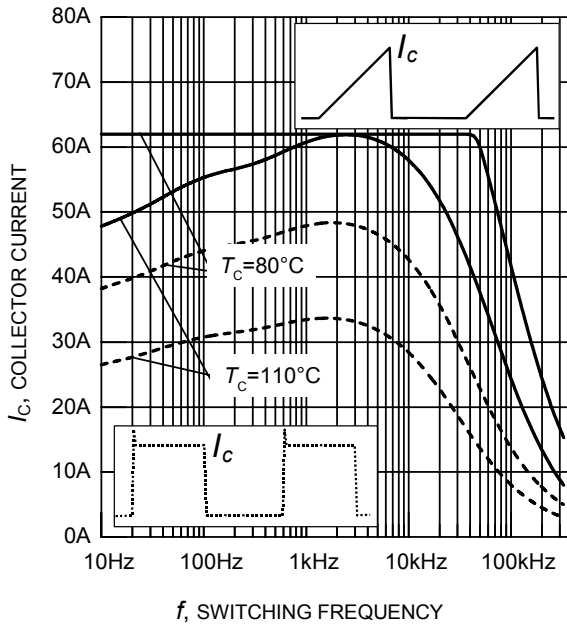


Figure 1. Collector current as a function of switching frequency
 ($T_j \leq 150^\circ\text{C}$, $D = 0.5$, $V_{CE} = 400\text{V}$,
 $V_{GE} = 0/+15\text{V}$, $R_G = 21\Omega$)

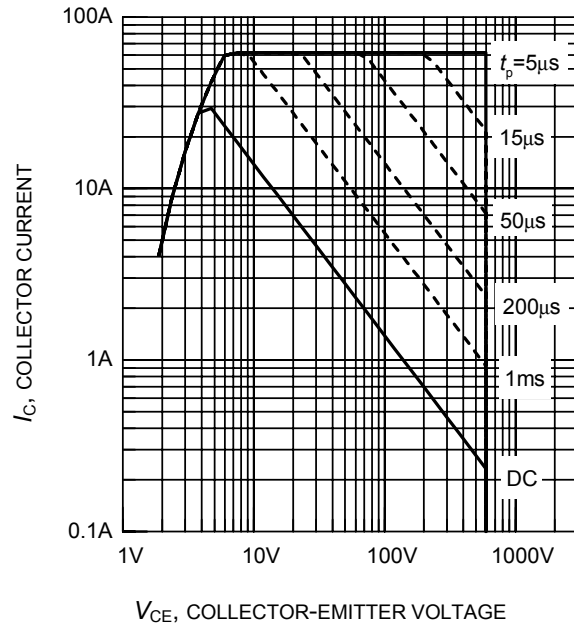


Figure 2. Safe operating area
 ($D = 0$, $T_C = 25^\circ\text{C}$, $T_j \leq 150^\circ\text{C}$)

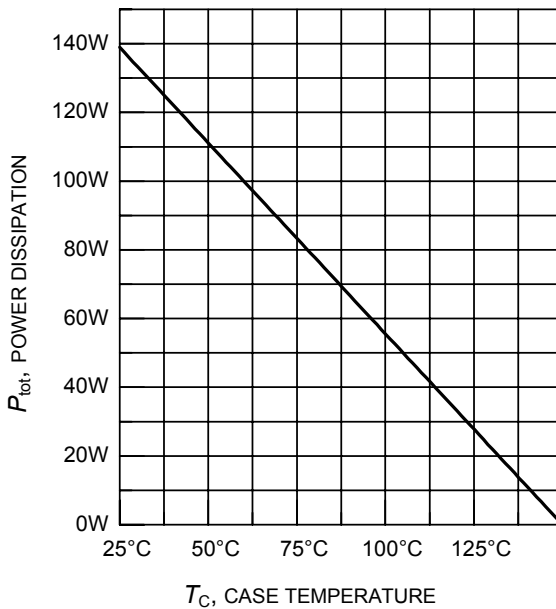


Figure 3. Power dissipation as a function of case temperature
 ($T_j \leq 150^\circ\text{C}$)

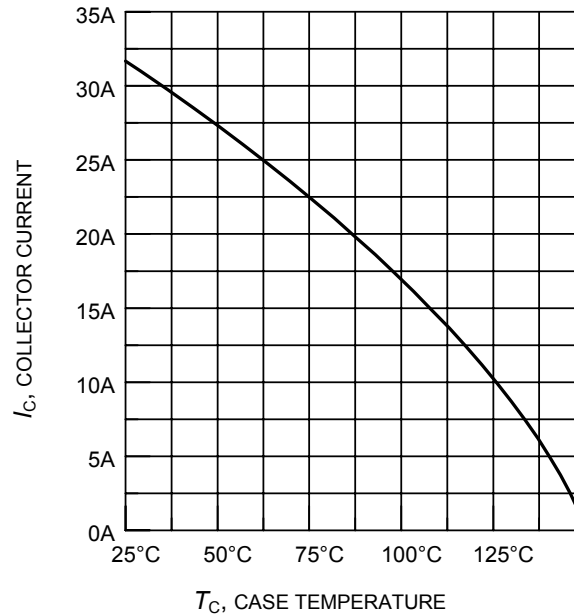


Figure 4. Collector current as a function of case temperature
 ($V_{GE} \leq 15\text{V}$, $T_j \leq 150^\circ\text{C}$)

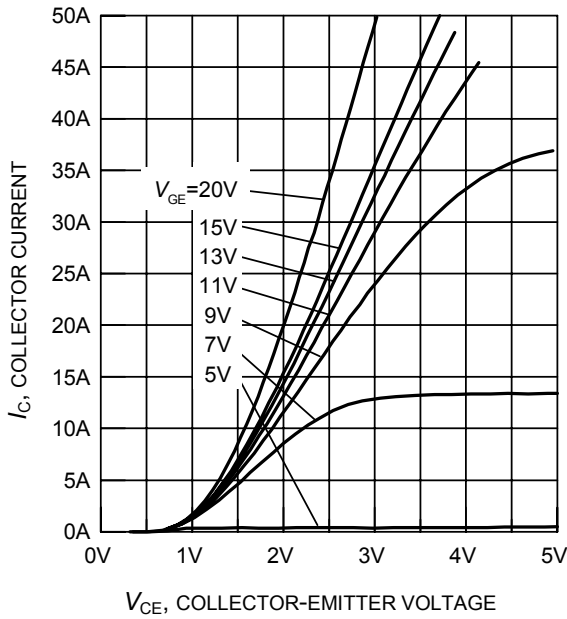


Figure 5. Typical output characteristics
($T_j = 25^\circ\text{C}$)

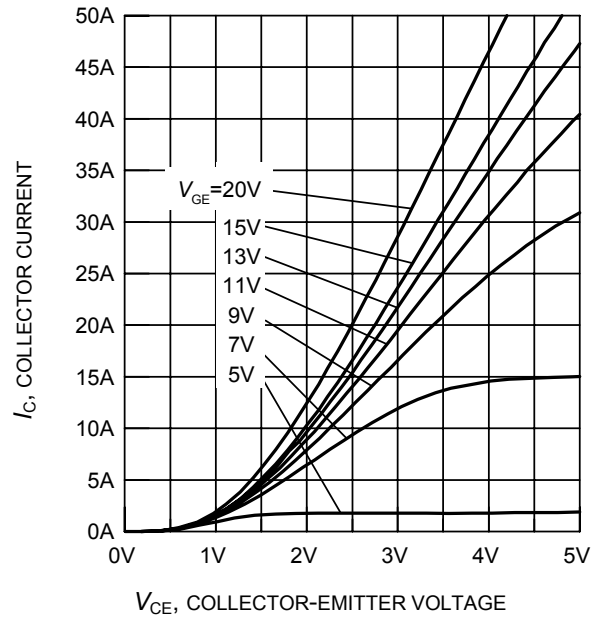


Figure 6. Typical output characteristics
($T_j = 150^\circ\text{C}$)

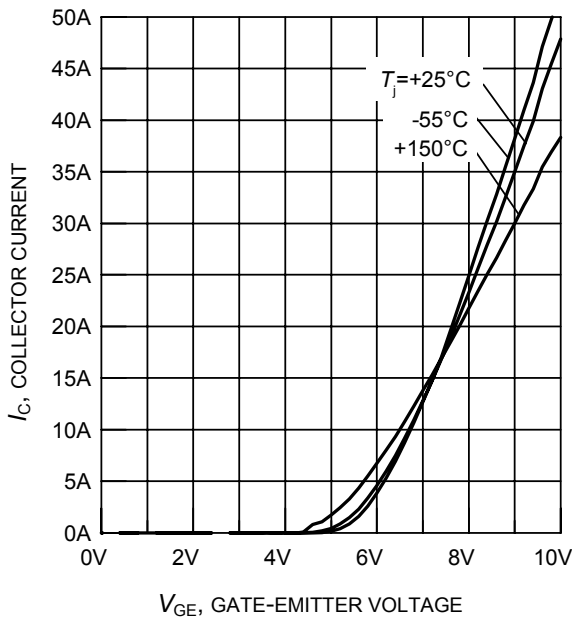


Figure 7. Typical transfer characteristics
($V_{CE} = 10\text{V}$)

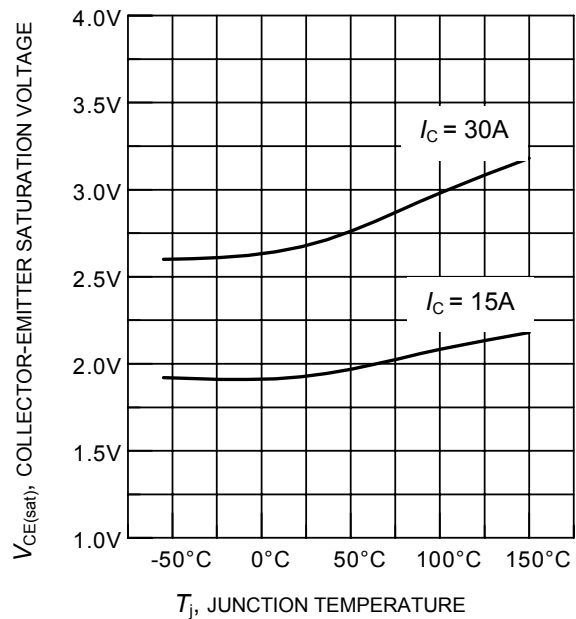


Figure 8. Typical collector-emitter saturation voltage as a function of junction temperature
($V_{GE} = 15\text{V}$)

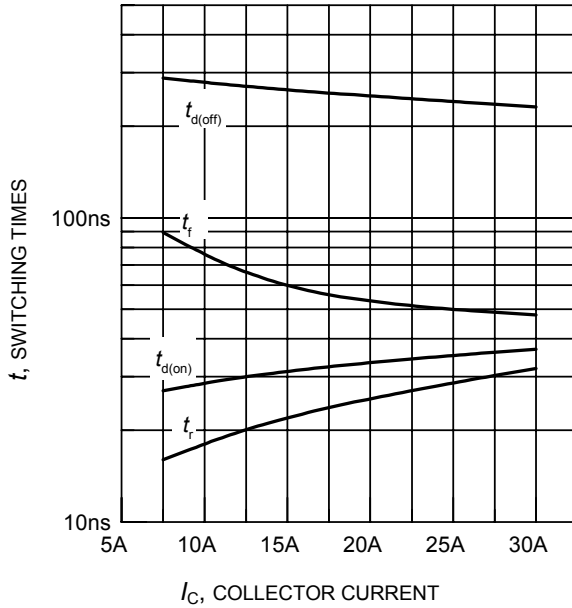


Figure 9. Typical switching times as a function of collector current
 (inductive load, $T_j = 150^\circ\text{C}$, $V_{CE} = 400\text{V}$, $V_{GE} = 0/+15\text{V}$, $R_G = 21\Omega$, Dynamic test circuit in Figure E)

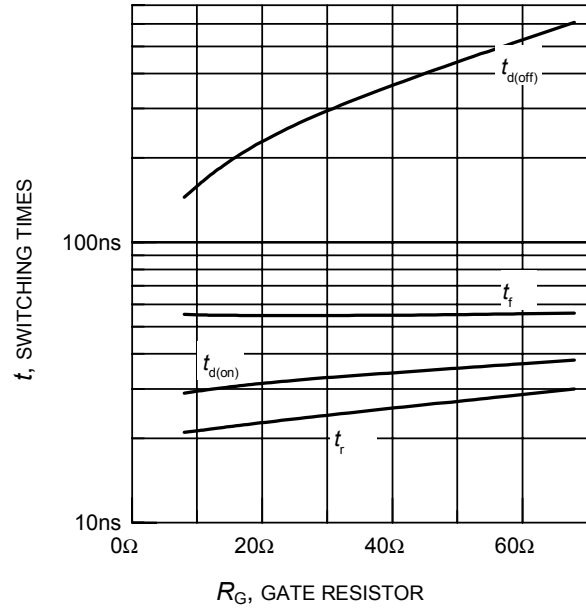


Figure 10. Typical switching times as a function of gate resistor
 (inductive load, $T_j = 150^\circ\text{C}$, $V_{CE} = 400\text{V}$, $V_{GE} = 0/+15\text{V}$, $I_C = 15\text{A}$, Dynamic test circuit in Figure E)

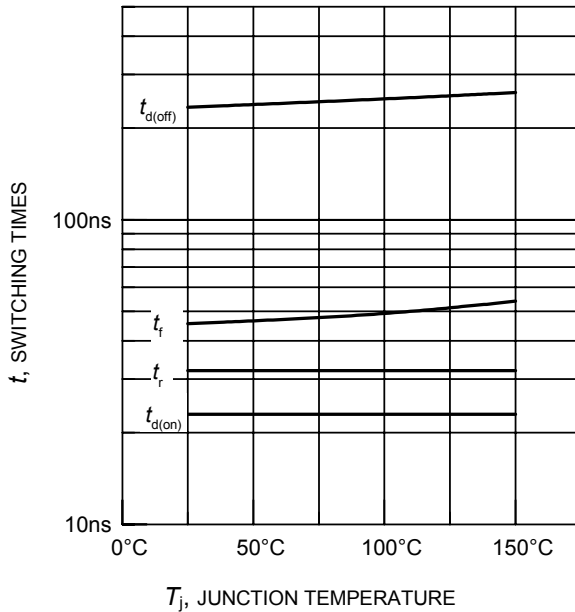


Figure 11. Typical switching times as a function of junction temperature
 (inductive load, $V_{CE} = 400\text{V}$, $V_{GE} = 0/+15\text{V}$, $I_C = 15\text{A}$, $R_G = 21\Omega$, Dynamic test circuit in Figure E)

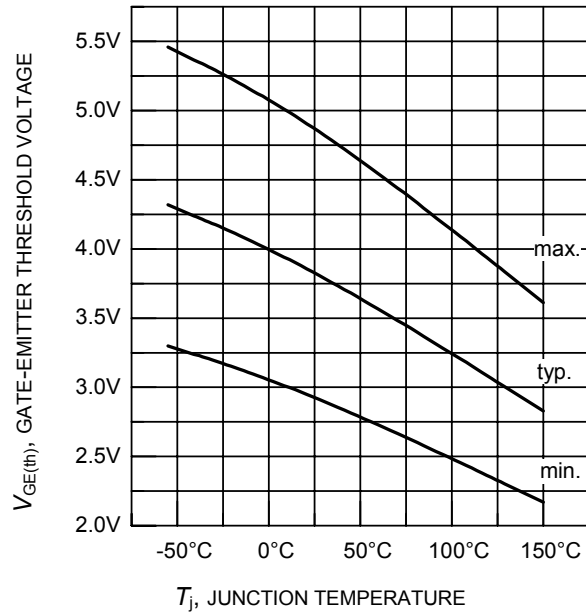


Figure 12. Gate-emitter threshold voltage as a function of junction temperature
 ($I_C = 0.4\text{mA}$)

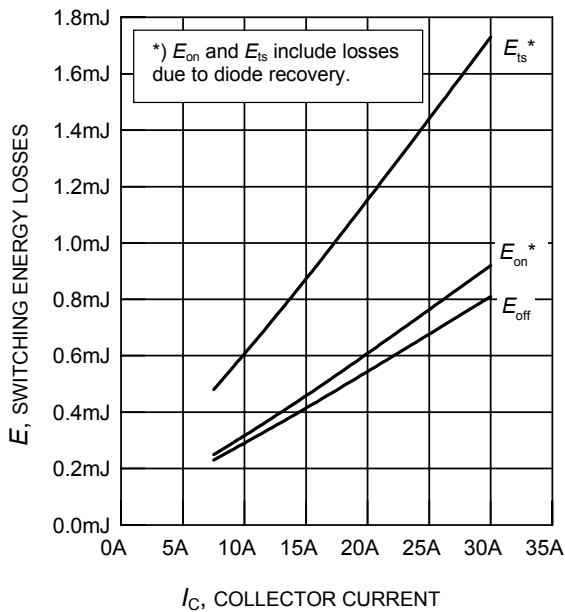


Figure 13. Typical switching energy losses as a function of collector current
 (inductive load, $T_j = 150^\circ\text{C}$, $V_{CE} = 400\text{V}$, $V_{GE} = 0/+15\text{V}$, $R_G = 21\Omega$, Dynamic test circuit in Figure E)

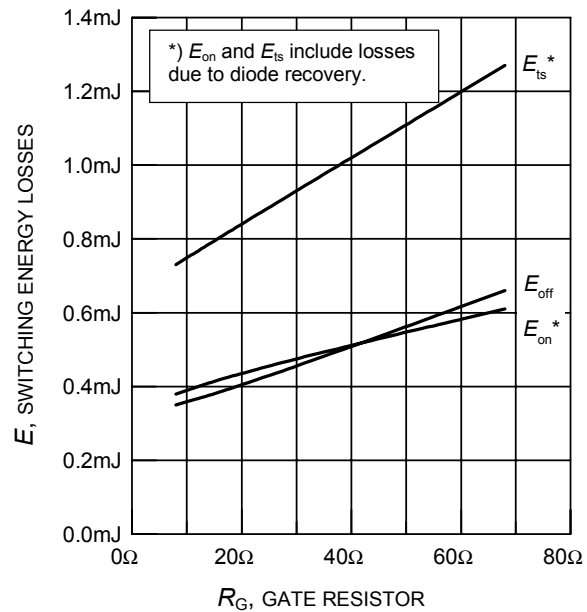


Figure 14. Typical switching energy losses as a function of gate resistor
 (inductive load, $T_j = 150^\circ\text{C}$, $V_{CE} = 400\text{V}$, $V_{GE} = 0/+15\text{V}$, $I_C = 15\text{A}$, Dynamic test circuit in Figure E)

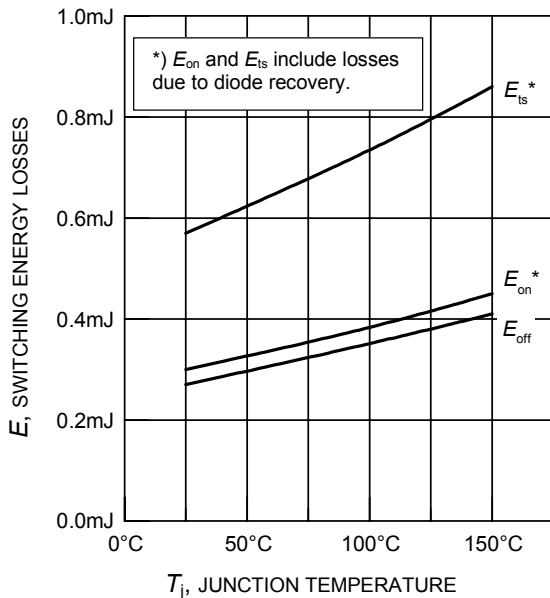


Figure 15. Typical switching energy losses as a function of junction temperature
 (inductive load, $V_{CE} = 400\text{V}$, $V_{GE} = 0/+15\text{V}$, $I_C = 15\text{A}$, $R_G = 21\Omega$, Dynamic test circuit in Figure E)

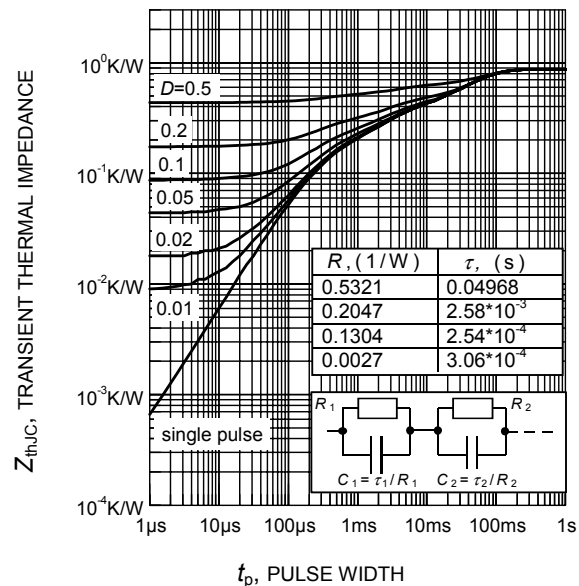


Figure 16. IGBT transient thermal impedance as a function of pulse width
 ($D = t_p / T$)

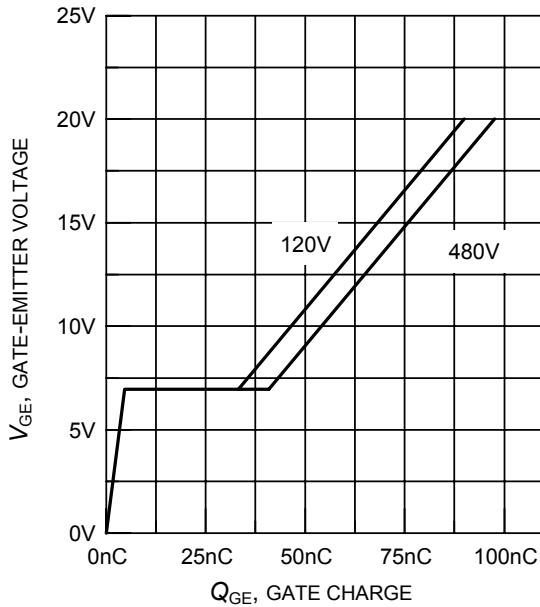


Figure 17. Typical gate charge
($I_C = 15A$)

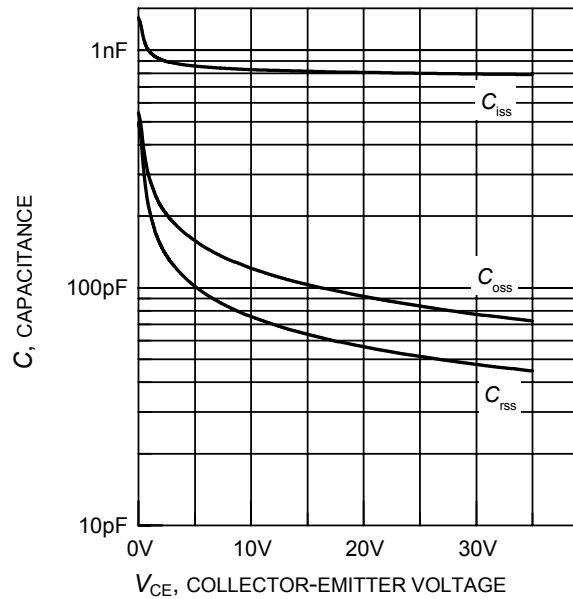


Figure 18. Typical capacitance as a function of collector-emitter voltage
($V_{GE} = 0V, f = 1MHz$)

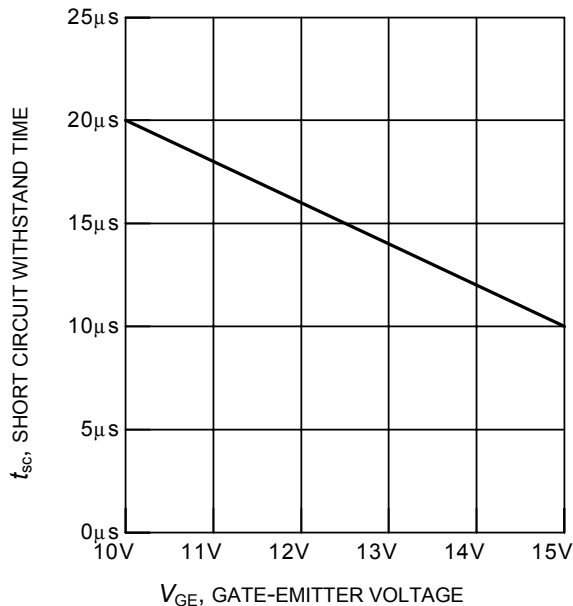


Figure 19. Short circuit withstand time as a function of gate-emitter voltage
($V_{CE} = 600V, \text{start at } T_j = 25^\circ C$)

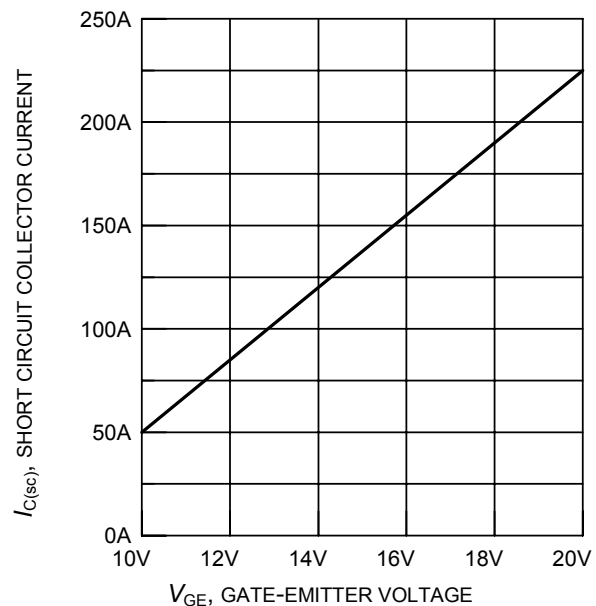
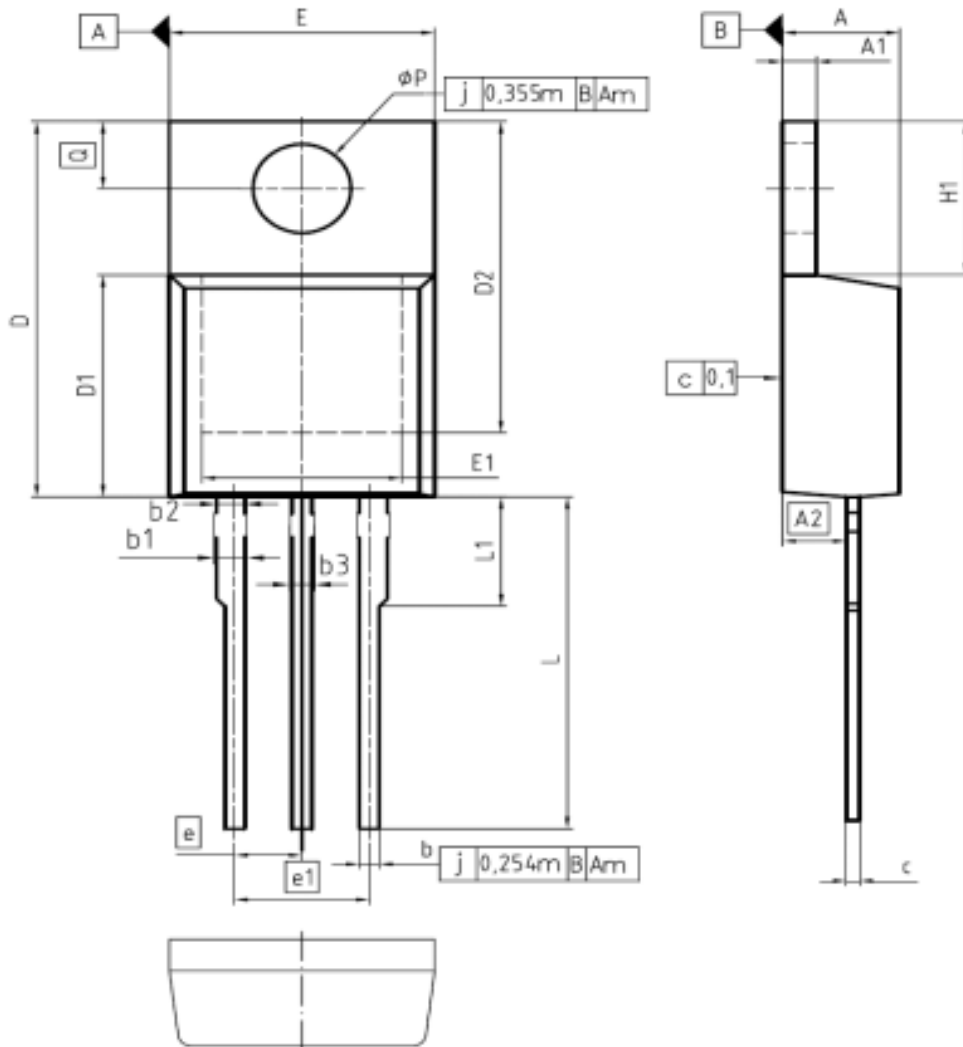


Figure 20. Typical short circuit collector current as a function of gate-emitter voltage
($V_{CE} \leq 600V, T_j = 150^\circ C$)

PG-TO-220-3-1



DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.30	4.57	0.169	0.180
A1	1.17	1.40	0.046	0.055
A2	2.15	2.72	0.085	0.107
b	0.65	0.86	0.026	0.034
b1	0.95	1.40	0.037	0.055
b2	0.95	1.15	0.037	0.045
b3	0.65	1.15	0.026	0.045
c	0.33	0.60	0.013	0.024
D	14.81	15.95	0.583	0.628
D1	8.51	9.45	0.335	0.372
D2	12.19	13.10	0.480	0.516
E	9.70	10.36	0.382	0.408
E1	6.50	8.60	0.256	0.339
e	2.54		0.100	
e1	5.08		0.200	
N	3		3	
H1	5.90	6.90	0.232	0.272
L	13.00	14.00	0.512	0.551
L1	-	4.80	-	0.189
aP	3.60	3.89	0.142	0.153
Q	2.60	3.00	0.102	0.118

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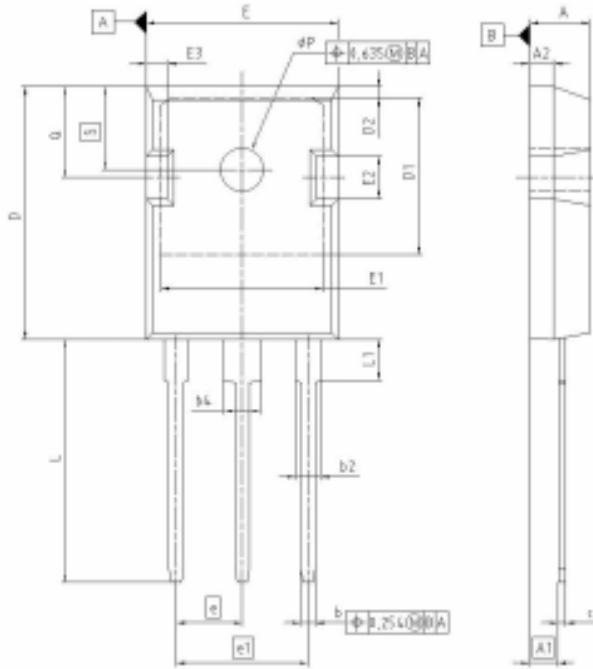
SCALE

EUROPEAN PROJECTION

ISSUE DATE
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REVISION
05

PG-T0247-3-21



DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.900	5.157	0.193	0.203
A1	2.275	2.507	0.090	0.099
A2	1.883	2.107	0.075	0.083
b	1.073	1.327	0.042	0.052
b2	1.063	2.588	0.075	0.102
b1	2.870	3.454	0.113	0.136
c	0.549	0.752	0.021	0.030
D	20.823	21.077	0.820	0.830
D1	17.323	17.831	0.682	0.702
D2	1.063	1.317	0.042	0.052
E	15.773	16.027	0.621	0.631
E1	13.893	14.147	0.547	0.557
E2	3.883	3.057	0.153	0.158
E3	1.803	1.907	0.071	0.076
e	5.450		0.215	
e1	10.000		0.430	
M	3		3	
L	20.953	20.307	0.789	0.799
L1	4.166	4.472	0.164	0.176
ϕP	3.059	3.061	0.120	0.121
Q	5.405	5.747	0.213	0.226
S	6.043	6.297	0.238	0.248

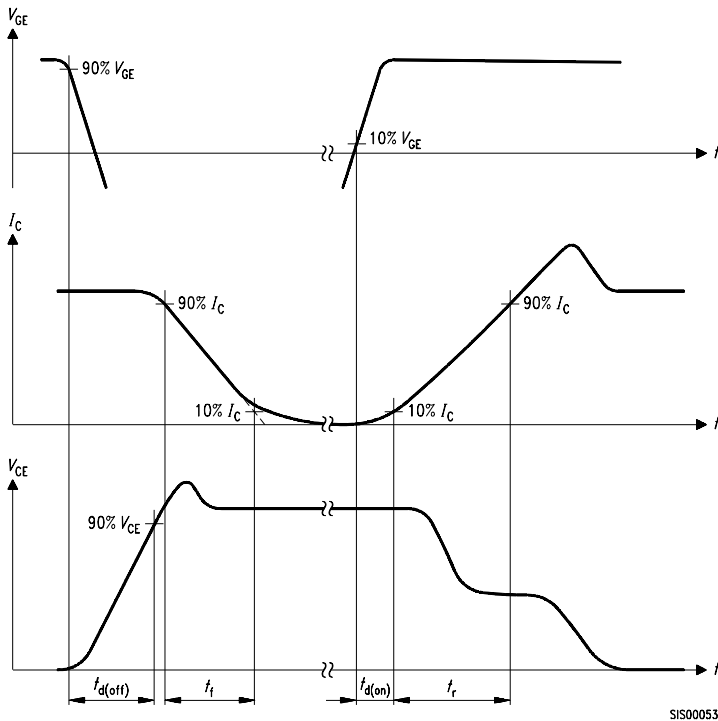


Figure A. Definition of switching times

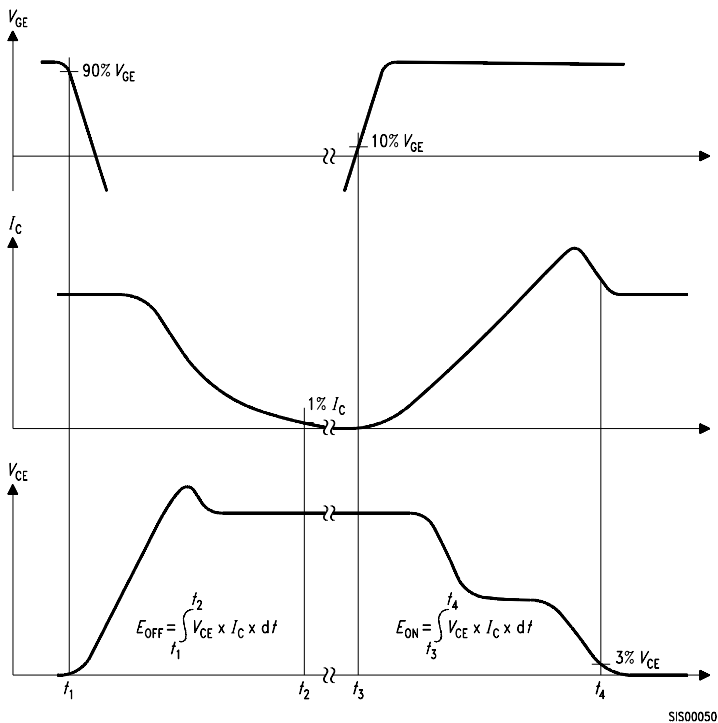


Figure B. Definition of switching losses

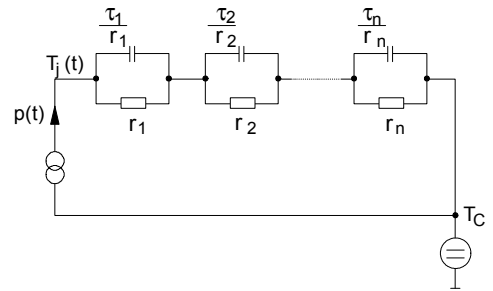
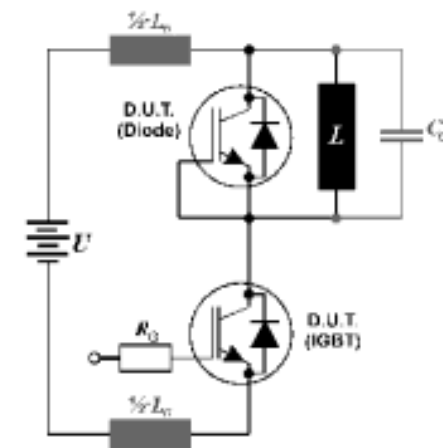


Figure D. Thermal equivalent circuit

Figure E. Dynamic test circuit
 Leakage inductance $L_{\sigma} = 180\text{nH}$
 and Stray capacity $C_{\sigma} = 250\text{pF}$.



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